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News Fact Sheet

Intel at Computex 2011

May 31-June 4, 2011 — Intel Corporation announced advancements leading to mobile industry growth through its Intel® Core™ and Atom™ Processor families, including the debut of a new line of thin mobile computers called Ultrabook™. Intel provided additional details about changes it is making to the Intel Core roadmap and reiterated its push to accelerate the pace of innovation for Intel Atom processor-based system-on-chips for mobile devices such as netbooks, smartphones and tablets.

2nd Generation Intel Core processors – The latest 2nd Generation Intel Core processors pave the way for a new class of thin, light, beautiful designs, and some of them will be showcased at Computex. These systems will begin to offer Intel® Smart Response Technology and Intel® Smart Connect Technology, and will be rolling out for the winter holidays this year.

Ultra-thin Laptops – Intel is showcasing 2nd Generation Intel Core processor-based ultra-thin laptops for consumers and business users. Ultra-thin laptops powered by the 2nd generation Intel Core processor family feature smart performance, enhanced battery life and a sleek design.

Responsiveness Features on 2nd Generation Intel Core processor-based laptops – Intel will demonstrate new responsiveness innovations coming to market in second half of 2011 on 2nd generation Intel® Core™ processor–based laptops.

- **Intel® Rapid Start Technology and Intel® Smart Connect Technology** – Hate to wait? Who doesn't? A great PC experience gives you what you need, when you need it. Intel has developed two technologies, Intel Rapid Start Technology and Intel Smart Connect Technology, to get what you need sooner. Intel Rapid Start Technology gets your system up and running faster from even the deepest sleep, saving time and battery life. Intel Smart Connect Technology keeps your e-mail and social networks updated automatically and ready when you are. Between faster wake-up times and always-synched info, you get to what you need sooner.

Intel® Smart Response Technology – Intel Smart Response Technology delivers fast access to your favorite applications and files by dynamically recognizing and automatically storing your most frequently used applications and files from your hard disk drive on a compact solid state drive.

All-in-One PCs – All-in-One (AIO) systems represent an emerging product category for desktop PCs. These systems integrate the entire PC into the display, and there will be many innovative designs on display at Computex. For example, LG Electronics* will be unveiling its first all-in-one PC, the V300, featuring 2nd Generation Intel Core processors, LG's 3D FPR display (the same display technology found in LG's CINEMA 3D TVs), and a triple camera system for superb multi-touch capability.

Intel also showcased the new **Thin Mini-ITX** board form factor, which is a standardized building block for building AIO PCs. By providing off-the-shelf components, Intel and its partners are helping make the AIO desktop more accessible to channel system integrators and local resellers worldwide.

Intel® Z68 Express Chipset and **Intel® Solid State Drive 311 Series** – Intel and several manufacturers will demonstrate systems based on the recently announced Intel Z68 Express Chipset and Intel Solid State Drive 311 series. The Intel Z68 Express Chipset is the newest addition to the Intel® 6 Series Chipset Family. Combined with 2nd Generation Intel Core processors, this desktop platform delivers the most flexibility and performance for the LGA 1155 socket, providing all tools necessary for power users to customize the PC experience. The Intel Z68 Express Chipset also enables the new Intel Smart Response Technology, a capability that implements storage I/O caching to provide users with faster response times for things such as system boot and application startup. In addition, Intel Z68 Express Chipset-based platforms provide support for 3rd party switchable graphics solutions for dynamic switching between built-in processor graphics and discrete graphics cards, and provide hardware-based authentication for secure PC gaming with Intel® Identity Protection Technology. Intel also offers the new Intel SSD 311 Series – a 20GB purpose-built, fast SLC NAND memory solid state drive, optimized for Intel Smart Response Technology, delivering a responsive PC performance experience.

Ivy Bridge Platform Demo – The Ivy Bridge platform is on track for 2012. Ivy Bridge uses the Sandy Bridge microarchitecture and takes advantage of Intel's 22nm manufacturing process with Tri-Gate 3-D transistors. With power optimized performance, Ivy Bridge will enable sleek form factors with fast responsiveness features. At the PC Client event during Computex, Mooly Eden, vice president and general manager of PC Client Group, will demonstrate an Ivy Bridge laptop, illustrating strong platform health.

Platform Innovation: USB 3.0 and Thunderbolt™ – The Ultrabook™ will enable a new user experience by accelerating a new class of mobile computers. These PCs will marry the performance and capabilities of today's laptops with tablet-like features and deliver a highly responsive and secure experience in a thin, light and elegant design. In addition, Intel will continue to innovate across all aspects of the platform, including the integration of USB 3.0 support into Intel's 2012 chipset. Thunderbolt technology, which debuted this year, will continue to appear in more devices and systems. Expect to see these two complementary technologies in many systems next year.

Intel® SSD 320 Series – The Intel SSD 320 Series, is the company's third-generation flagship client drive (replacing the popular Intel® X25-M) based on 25nm multi-level cell (MLC) NAND flash memory. The Intel SSD 320 offers advanced architecture enabling

robust, reliable SSDs with enhanced security features for desktop/laptops PCs or server data center storage.

Intel® SSD 510 Series – The Intel® SSD 510 Series is a SATA III 6 Gigabits per second (Gbps) drive supporting fast data transfers of up to 500 megabytes per second (MB/s) and sequential read speeds at up to 315MB/s to transfer more data in less time. This makes it ideal for demanding gamers, media creators, performance-intensive workstation users and any technology enthusiast.

Intel Atom™ Processor Roadmap – The Atom processor will outpace [Moore's Law](), accelerating from 32nm through 22nm to 14nm within 3 successive years. Having a cadence of a new process generation every year will result in significant reduction in transistor leakage, lower active power and increase of transistor density, enabling more powerful smartphones, tablets and netbooks with more features and long battery life.

"Medfield" at Computex – Intel highlighted its first purpose-built 32nm platform for smartphones and tablets. The platform has been optimized for both low power and high performance and will deliver a great all around experience, including long use-time, rich media and gaming, and advanced imaging capabilities.

Next-generation tablet solutions based on "Medfield" will provide lower power, a smaller footprint and more integration of features and performance for this market segment. "Medfield" will enable sub-9mm tablets that weigh less than 1.5 pounds and provide all day battery life. In production later this year, the platform will enable sub-9mm designs that weigh less than 1.5 pounds for tablet designs in market the first half of 2012. It will support a range of operating systems including Android and MeeGo.

- **Android 3.0 ("Honeycomb") Runs on Intel Tablets** – Intel also will highlight Android "Honeycomb" running on "Medfield," and the Intel® Atom™ processor Z670 on-stage at the Computex opening keynote on May 31.

Upcoming "Cedar Trail" Netbook Platform – Intel continues to highlight the upcoming Intel Atom™ platform for netbooks, codenamed "Cedar Trail," the solution of choice for the next generation of cool, quiet, sleek, fanless and innovative netbooks, entry desktop, and all-in-one designs. Based on Intel's leading-edge 32nm process technology, "Cedar Trail" features improved graphics capabilities including Blu-Ray* Disc 2.0 support, a dedicated media engine for full 1080p HD playback, and additional digital display options including HDMI and DP. The "Cedar Trail" platform also will support Intel® Wireless Display and responsiveness features such as Intel® Rapid Start Technology and Intel® Smart Connect so that consumers can start up in just seconds and have their content always updated. Consumers can look forward to a new generation of innovative mobile and desktop designs based on the "Cedar Trail" platform in the second half of 2011.

Next Wave of Companion Computing – Intel will unveil "Keeley Lake," an innovative, newly developed convertible design for the next generation of companion computing. Based on the upcoming Intel Atom netbook platform, codenamed "Cedar Trail," "Keeley Lake" features Intel® Advanced Cooling Technology to help enable sleek, convertible designs. Whether creating with a keyboard or browsing with touch, "Keeley Lake" will offer customers the best of

both worlds at less than 20mm thin. Intel has enabled ODMs with the "Keeley Lake" design; the company has already started to see the demand.

MeeGo™ Device Momentum Continues – The ecosystem around MeeGo-based netbooks expands with the introduction of devices including the 2nd-generation Acer* Aspire One Happy series, Asus* Eee PC X101, Lenovo* IdeaPad S100 and Samsung* N100 at Computex. These systems are based on the new, 1.33 GHz single-core Intel® Atom™ processor N435. The netbooks will provide new levels of affordability for market expansion. Acer and Asus netbooks will come pre-loaded with the Intel AppUp^{SM} center in the second half of 2011.

Intel AppUp^{SM} center Expands – In less than a year, the Intel AppUp center and its associated stores have been downloaded by more than 1 million consumers. This number will continue to grow quickly as the Intel AppUp center expands to support a range of devices and new associate stores. Acer* (OEM), India-based Reliance Communications* (telco), Indonesia-based SpeedUp* (MLW Telecom) (telco), Evernew* (retailer), Malaysia-based FOSA* (retailer), U.S.-based Awaken* (retailer) and Datavision* (retailer) are the latest companies to announce plans to join the Intel AppUp center. The Intel AppUp center proves to be a flexible business model for different types of partners. Joining customers including Asus*, Best Buy* and the Home Shopping Network*, these companies will offer customers a wide selection of applications for Windows* or MeeGo on consumer laptops, netbooks, and tablets.

- **Intel AppUp Center: MeeGo Edition** – The Intel AppUp center has opened a beta store for applications created for MeeGo-based netbooks. To support the launch, Acer*, Asus* and Fujitsu* netbooks will be sold with pre-loaded copies of the application store starting in the second half of 2011. Moreover, the Intel AppUp center's support for MeeGo-based tablet applications is now in beta and a preview is available at the Intel booth.
- **New Languages Added** – The Intel AppUp developer program now supports applications in German and Spanish, thereby expanding market opportunities for developers. Starting May 31, applications in these languages can be submitted to the program through appdeveloper.intel.com for validation and eventual distribution through the Intel AppUp center and associated application stores.

Cloud 2015 – Intel's vision has three key elements: A "federated" or more united cloud that allows enterprises to share data across internal and external clouds; an "automated" network that allows the secure movement of applications and resources between clouds; and a "device-aware" cloud that knows what types of applications, commands and processing should take place in the cloud or on your laptop, smartphone or other device – thus taking a user and specific device's unique features into account. Intel also helped create the Open Data Center Alliance (ODCA), a coalition of more than 150 leading businesses that together represent nearly $85 billion in annual IT investment and that have cloud research or projects underway. The alliance is defining future hardware and software requirements that lead to more open and interoperable cloud and data center solutions.